PRESS RELEASE

Sanmina-SCI Contacts:
Michael Kovacs
Director, Corporate Marketing
+1.408.964.3142
michael.kovacs@sanmina-sci.com

Paige Bombino
Investor Relations
+1.408.964.3610

FOR IMMEDIATE RELEASE

SANMINA-SCI ANNOUNCES NEW REVOLUTIONARY SUPERBC™ TECHNOLOGY FOR CHIP SUBSTRATES AND HIGH-PERFORMANCE PRINTED CIRCUIT BOARDS AT APEX 2008

SuperBC™ Provides 40-80 Nanofarads Per Square Inch Capacitance Density with Optional 100 Percent ESD Protection

SAN JOSE, Calif. – April 2, 2008 – Sanmina-SCI Corporation (Nasdaq NM: SANM), a leading global Electronics Manufacturing Services (EMS) company and high-performance printed circuit board (PCB) fabricator, today announced SuperBC™ at Apex 2008 in Las Vegas. This new patent pending technology delivers next-generation levels of performance for Buried Capacitance® applications for use in providing bypass capacitance inside silicon chip packages and high-performance PCBs.

SuperBC also includes a layer of Sanmina-SCI's patent pending eESD™ embedded electrostatic discharge (ESD) protection technology which, if designed properly, can protect 100 percent of the I/O pins on a chip or PCB from voltage transients as high as 30K volts. Sanmina-SCI's PCB Division plans to collaborate with their joint development partner Shocking Technologies and BC Licensee Oak-Mitsui to integrate Xstatic™ voltage switchable dielectric (VSD) material with ultra-thin layers of nanopowder loaded Faradflex™ material.

"SuperBC laminate will provide next-generation levels of capacitance density along with other enabling performance characteristics," stated George Dudnikov, Senior Vice President and Chief Technology Officer for Sanmina-SCI's PCB and Backplane Divisions. "The technology uses a base 1 or 2 mil BC core onto which additional 8 micron or thinner high Dk dielectric layers are added to form a composite capacitance core. Multiple dielectrics can be added to either boost bulk planar capacitance values or segregate the Power Distribution System

(PDS) by different voltage levels or noise budgets. To date, we are producing SuperBC cores with 45 nanofarads per square inch of capacitance in an overall thickness of less than 6 mils. The result is 90 times the capacitance density of ZBC2000, the industry market-leading capacitance material, in a thinner construction than a standard 4 mil dielectric power ground layer," continued Dudnikov.

SuperBC can also include a layer of eESD which uses a thin continuous layer of Shocking Technologies Xstatic VSD material under a ground plane inside the PCB. The VSD material is programmed to switch from being a pure dielectric insulator to pure electrical conductor, dissipate the ESD transient to ground, and then reset itself – all in less than a nanosecond. Testing has shown that protection levels up to 30K volts are achievable.

"As processor frequencies and bandwidth requirements continue to increase, PDS designers are looking for more and more low inductance capacitance for bypass," added Dudnikov. SuperBC can be utilized in high-performance server and telecom applications where it can significantly reduce, if not totally eliminate, the need for surface bypass or specialty capacitors. It will also be very enabling as a core for chip packaging substrates where higher levels of distributed capacitance can be placed very close to the silicon chip. With the addition of a layer of eESD, critical electrostatic discharge protection can be added to improve reliability of the electronic system."

SuperBC will be available from Sanmina-SCI, plus a select number of licensees. For more information on Sanmina-SCI's PCB Division, visit the PCB Resource web page at http://www.sanmina-sci.com/Solutions/pcb_resource.html or call +1.408.964.4614.

About Sanmina-SCI

Sanmina-SCI Corporation is a leading electronics contract manufacturer serving the fastest-growing segments of the global Electronics Manufacturing Services (EMS) market. Recognized as a technology leader, Sanmina-SCI provides end-to-end manufacturing solutions, delivering unsurpassed quality and support to OEMs primarily in the communications, defense and aerospace, industrial and medical instrumentation, multimedia, computing and storage, and automotive technology sectors. Sanmina-SCI has facilities strategically located in key regions throughout the world. More information regarding the company is available at http://www.sanmina-sci.com.

About Shocking Technologies, Inc.

Shocking Technologies is a private, venture capital backed startup located in San Jose, California, focused on the development of its voltage switchable materials and its applications. For more information, please contact +1.408.434.2211 or email info@shockingtech.com.

About Oak-Mitsui Technologies

Oak-Mitsui Technologies (OMT) provides FaradFlex® embedded capacitance material. Located in Hoosick Falls, NY, OMT was formed to leverage the core capabilities of Mitsui-Kinzoku into new business ventures. For more information, please contact +1.518.686.4961 or email faradflex.sales@oakmitsui.com.

Sanmina-SCI Safe Harbor Statement

The foregoing, including the discussion regarding the Company's future prospects, contains certain forward-looking statements that involve risks and uncertainties, including uncertainties associated with economic conditions in the electronics industry, particularly in the principal industry sectors served by the Company, changes in customer requirements and in the volume of sales to principal customers, the ability of Sanmina-SCI to effectively assimilate acquired businesses and achieve the anticipated benefits of its acquisitions, and competition and technological change. The Company's actual results of operations may differ significantly from those contemplated by such forward-looking statements as a result of these and other factors, including factors set forth in the Company's fiscal year 2007 Annual Report on Form 10-K filed on November 28, 2007 and the other reports, including quarterly reports on Form 10-Q and current reports on Form 8-K, that the Company files with the Securities Exchange Commission.

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